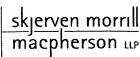




T: 949-718-5200 F: 949-718-6799 San Jose, CA San Francisco, CA



Docket No.: M-12589 US

February 22, 2002

BOX PATENT APPLICATION Commissioner for Patents Washington, D.C. 20231

Enclosed herewith for filing is a patent application, as follows:

Hua Ji Inventor:

HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio Trench Title:

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This Transmittal Letter (in duplicate) page(s) Specification (not including claims)

page(s) Claims

page Abstract Sheet(s) of Drawings

page(s) Declaration For Patent Application and Power of Attorney

page(s) Recordation Form Cover Sheet (in duplicate)

page(s) Assignment

CLAIMS AS FILED

For Total Claims	Number <u>Filed</u> 29	-20	=	Number <u>Extra</u> 9	x	Rate \$18.00	=	\$ \$	Basic Fee <u>740.00</u> 162.00
Independent Claims	2	-3		0	х	\$84.00	=	\$	0.00
Fee of for the first filing of one or more multiple dependent claims per application								\$	
Fee for Request for Extension of Time								\$	

Please make the following charges to Deposit Account 19-2386:

Total fee for filing the patent application in the amount of

The Commissioner is hereby authorized to charge any additional fees which may be

required, or credit any overpayment to Deposit Account 19-2386.

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Respectfully submitted,

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Alan H. MacPherson Attorney for Applicant

Reg. No. 24,423

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